

www.vishay.com

Vishay Siliconix

N-Channel 100 V (D-S) MOSFET

Top View

Bottom View

PRODUCT SUMMARY					
V _{DS} (V)	100				
$R_{DS(on)}$ max. (Ω) at $V_{GS} = 10 \text{ V}$	0.00480				
$R_{DS(on)}$ max. (Ω) at $V_{GS} = 7.5 \text{ V}$	0.00505				
Q _g typ. (nC)	55				
I _D (A)	95				
Configuration	Single				

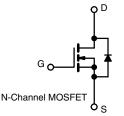
FEATURES

- TrenchFET® Gen IV power MOSFET
- Very low R_{DS} Q_g figure-of-merit (FOM)
- Tuned for the lowest R_{DS} Q_{oss} FOM
- Top side cooling feature provides additional venue for thermal transfer
- 100 % R_g and UIS tested
- Material categorization: for definitions of compliance please see <u>www.vishay.com/doc?99912</u>

APPLICATIONS

- Synchronous rectification
- Primary side switch
- DC/DC converters
- OR-ing
- Power supplies
- Motor drive control
- Battery and load switch





ORDERING INFORMATION	
Package	PowerPAK SO-8DC
Lead (Pb)-free and halogen-free	SiDR668DP-T1-GE3

PARAMETER		SYMBOL	LIMIT	UNIT	
Drain-source voltage		V _{DS}	100	V	
Gate-source voltage		V _{GS}	± 20	V	
	T _C = 25 °C		95		
Continuous drain current (T _J = 150 °C)	T _C = 70 °C	1 .	76		
	T _A = 25 °C	- I _D -	23.2 b, c		
	T _A = 70 °C		18.6 ^{b, c}	Α .	
Pulsed drain current (t = 100 µs)		I _{DM}	200		
Continuous source-drain diode current	T _C = 25 °C		94		
	T _A = 25 °C	ls	5.6 ^{b, c}		
Single pulse avalanche current	. 0.111	I _{AS}	35		
Single pulse avalanche energy L = 0.1 m		E _{AS}	E _{AS} 61.2		
	T _C = 25 °C		125		
Maximum power dissipation	T _C = 70 °C		80	14/	
	T _A = 25 °C	P _D	6.25 ^{b, c}	W	
	T _A = 70 °C	1	4 b, c		
Operating junction and storage temperature range		T _J , T _{stg}	-55 to +150	20	
Soldering recommendations (peak temperature) c			260	°C	

THERMAL RESISTANCE RATINGS					
PARAMETER		SYMBOL	TYPICAL	MAXIMUM	UNIT
Maximum junction-to-ambient ^b	t ≤ 10 s	R _{thJA}	15	20	
Maximum junction-to-case (drain)	Steady state	R _{thJC}	0.8	1	°C/W
Maximum junction-to-case (source)	Steady state	R _{thJC}	1.1	1.4	

Notes

- a. Package limited
- b. Surface mounted on 1" x 1" FR4 board
- c. t = 10 s
- d. See solder profile (<u>www.vishay.com/doc?73257</u>). The PowerPAK SO-8DC is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection
- e. Rework conditions: manual soldering with a soldering iron is not recommended for leadless components
- f. Maximum under steady state conditions is 54 °C/W
- g. $T_C = 25 \,^{\circ}C$



www.vishay.com

Vishay Siliconix

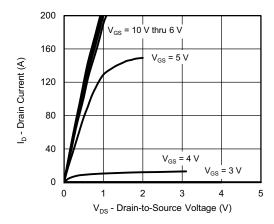
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT
Static					•	
Drain-source breakdown voltage	V_{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	100	-	-	V
V _{DS} temperature coefficient	$\Delta V_{DS}/T_{J}$	I _D = 10 mA	-	70	-	
V _{GS(th)} temperature coefficient	$\Delta V_{GS(th)}/T_J$	I _D = 250 μA	-	-7.2	-	mV/°C
Gate-source threshold voltage	V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 250 \mu A$	2	-	3.4	V
Gate-source leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$	-	-	100	nA
Zoro goto voltago droin overent	,	V _{DS} = 100 V, V _{GS} = 0 V	-	-	1	
Zero gate voltage drain current	I _{DSS}	V _{DS} = 100 V, V _{GS} = 0 V, T _J = 70 °C	-	-	15	μA
On-state drain current ^a	I _{D(on)}	$V_{DS} \ge 10 \text{ V}, V_{GS} = 10 \text{ V}$	40	-	-	Α
Drain actives on etata registance 8	В	V _{GS} =10 V, I _D = 20 A	-	0.00400	0.00480	_
Drain-source on-state resistance a	R _{DS(on)}	V _{GS} = 7.5 V, I _D = 15 A	-	0.00420	0.00505	Ω
Forward transconductance ^a	9 _{fs}	V _{DS} = 15 V, I _D = 20 A	-	85	-	S
Dynamic ^b						
Input capacitance	C _{iss}		-	5400	-	
Output capacitance	C _{oss}	V _{DS} = 50 V, V _{GS} = 0 V, f = 1 MHz - 28		280	-	рF
Reverse transfer capacitance	C _{rss}		-	38	-	
Total gata abaysa	0	V _{DS} = 50 V, V _{GS} = 10 V, I _D = 10 A	-	72	108	
Total gate charge	Q_g		-	55	83	
Gate-source charge	Q _{gs}	$V_{DS} = 50 \text{ V}, V_{GS} = 7.5 \text{ V}, I_D = 10 \text{ A}$	-	21.6	-	nC
Gate-drain charge	Q_{gd}		-	12	-	
Output charge	Q _{oss}	V _{DS} = 50 V, V _{GS} = 0 V	-	61	-	
Gate resistance	R _g	f = 1 MHz	0.3	0.9	1.6	Ω
Turn-on delay time	t _{d(on)}		-	17	34	
Rise time	t _r	$V_{DD} = 50 \text{ V}, \text{ R}_{L} = 5 \Omega, \text{ I}_{D} \cong 10 \text{ A},$	-	22	44	
Turn-off delay time	t _{d(off)}	$V_{GEN} = 10 \text{ V}, R_g = 1 \Omega$	-	30	60	
Fall time	t _f		-	11	22	
Turn-on delay time	t _{d(on)}		-	22	44	ns
Rise time	t _r	$V_{DD} = 50 \text{ V}, \text{ R}_L = 5 \Omega, \text{ I}_D \cong 10 \text{ A},$	-	25	50	
Turn-off delay time	t _{d(off)}	V_{GEN} = 7.5 V, R_g = 1 Ω	-	38	76	
Fall time	t _f		-	28	56	
Drain-Source Body Diode Characteristi	cs					
Continuous source-drain diode current	I _S	T _C = 25 °C	-	-	94	Λ
Pulse diode forward current	I _{SM}		-	-	200	Α
Body diode voltage	V_{SD}	I _S = 5 A, V _{GS} = 0 V	-	0.73	1.1	V
Body diode reverse recovery time	t _{rr}		-	59	118	ns
Body diode reverse recovery charge	Q _{rr}	1 10 A 3:/dt 100 A/ - T 05 00	-	115	230	nC
Reverse recovery fall time	ta	$I_F = 10 \text{ A}, \text{ di/dt} = 100 \text{ A/}\mu\text{s}, T_J = 25 ^{\circ}\text{C}$	-	37	-	
Reverse recovery rise time	t _b		-	22	-	ns

Notes

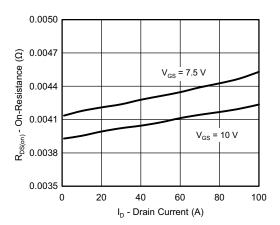
- a. Pulse test; pulse width \leq 300 μ s, duty cycle \leq 2 %
- b. Guaranteed by design, not subject to production testing

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

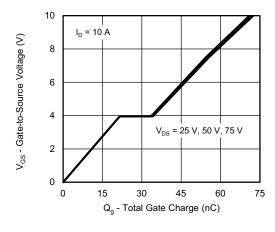




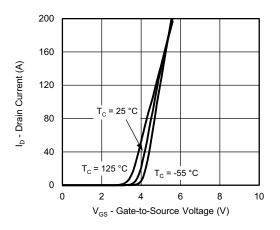
Output Characteristics



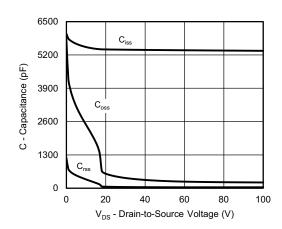
On-Resistance vs. Drain Current and Gate Voltage



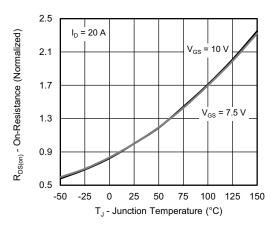
Gate Charge



Transfer Characteristics

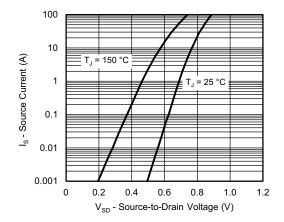


Capacitance

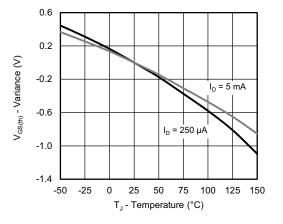


On-Resistance vs. Junction Temperature

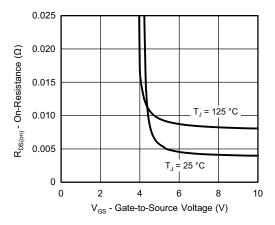




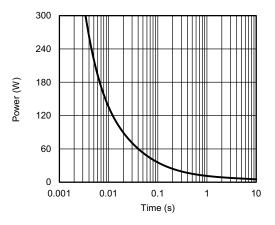
Source-Drain Diode Forward Voltage



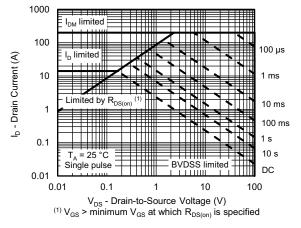
Threshold Voltage



On-Resistance vs. Gate-to-Source Voltage

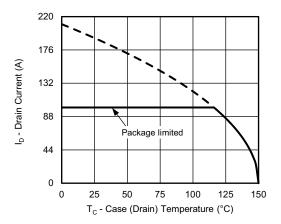


Single Pulse Power, Junction-to-Ambient

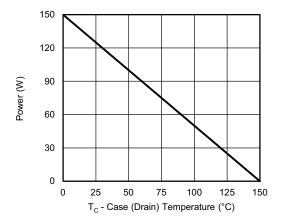


Safe Operating Area, Junction-to-Ambient

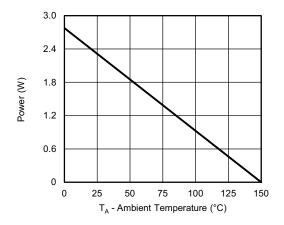




Current Derating a





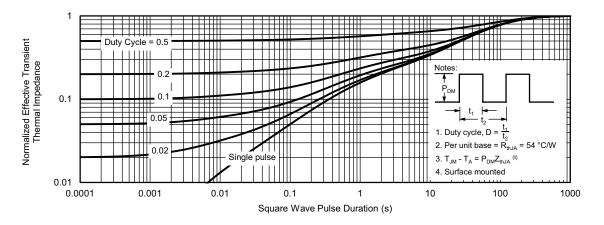


Power, Junction-to-Ambient

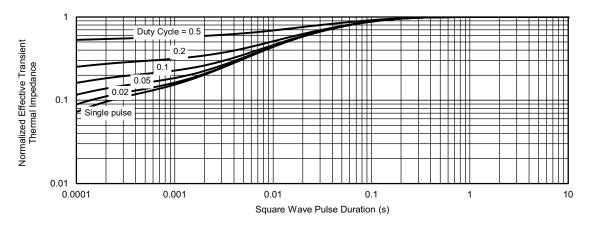
Note

a. The power dissipation P_D is based on T_J max. = 150 °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.

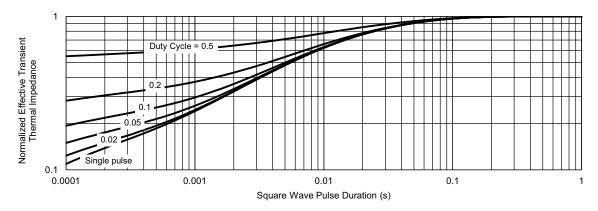




Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Case (Drain)

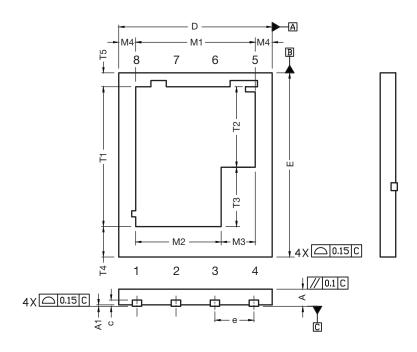


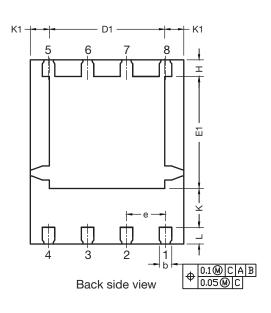
Normalized Thermal Transient Impedance, Junction-to-Case (Source)

Vishay Siliconix maintains worldwide manufacturing capability. Products may be manufactured at one of several qualified locations. Reliability data for Silicon Technology and Package Reliability represent a composite of all qualified locations. For related documents such as package / tape drawings, part marking, and reliability data, see www.vishay.com/ppg?75751.

Vishay Siliconix

PowerPAK® SO-8 Double Cooling Case Outline





DIM.	MILLIMETERS			INCHES			
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.	
Α	0.51	0.56	0.61	0.012	0.014	0.016	
A1	0.00	0.02	0.05	0.000	0.0008	0.002	
b	0.36	0.41	0.46	0.014	0.016	0.018	
С	0.15	0.20	0.25	0.006	0.008	0.010	
D	4.90	5.00	5.10	0.193	0.197	0.201	
D1	3.71	3.76	3.81	0.146	0.148	0.150	
е		1.27 BSC			0.050 BSC		
Е	5.90	6.00	6.10	0.232	0.236	0.240	
E1	3.60	3.65	3.70	0.142	0.144	0.146	
Н	0.49	0.54	0.59	0.019	0.021	0.023	
K	1.22	1.27	1.32	0.048	0.050	0.052	
K1		0.64 typ.		0.025 typ.			
L	0.49	0.54	0.59	0.019	0.021	0.023	
M1	3.85	3.90	3.95	0.152	0.154	0.156	
M2	2.74	2.79	2.84	0.108	0.110	0.112	
M3	1.06	1.11	1.16	0.042	0.044	0.046	
M4		0.56 typ.		0.022 typ.			
N		8		8			
T1	4.51	4.56	4.61	0.178	0.180	0.182	
T2	2.58	2.63	2.68	0.102	0.104	0.106	
T3	1.88	1.93	1.98	0.074	0.076	0.078	
T4	0.97 typ.			0.038 typ.			
T5	0.48 typ.			0.019 typ.			

DWG: C040

DWG: 6048

Revison: 11-Jul-16

Document Number: 75846



RECOMMENDED MINIMUM PADS FOR PowerPAK® SO-8 Single



Recommended Minimum Pads Dimensions in Inches/(mm)

Return to Index

APPLICATION NOTE



Legal Disclaimer Notice

Vishay

Disclaimer

ALL PRODUCT, PRODUCT SPECIFICATIONS AND DATA ARE SUBJECT TO CHANGE WITHOUT NOTICE TO IMPROVE RELIABILITY, FUNCTION OR DESIGN OR OTHERWISE.

Vishay Intertechnology, Inc., its affiliates, agents, and employees, and all persons acting on its or their behalf (collectively, "Vishay"), disclaim any and all liability for any errors, inaccuracies or incompleteness contained in any datasheet or in any other disclosure relating to any product.

Vishay makes no warranty, representation or guarantee regarding the suitability of the products for any particular purpose or the continuing production of any product. To the maximum extent permitted by applicable law, Vishay disclaims (i) any and all liability arising out of the application or use of any product, (ii) any and all liability, including without limitation special, consequential or incidental damages, and (iii) any and all implied warranties, including warranties of fitness for particular purpose, non-infringement and merchantability.

Statements regarding the suitability of products for certain types of applications are based on Vishay's knowledge of typical requirements that are often placed on Vishay products in generic applications. Such statements are not binding statements about the suitability of products for a particular application. It is the customer's responsibility to validate that a particular product with the properties described in the product specification is suitable for use in a particular application. Parameters provided in datasheets and / or specifications may vary in different applications and performance may vary over time. All operating parameters, including typical parameters, must be validated for each customer application by the customer's technical experts. Product specifications do not expand or otherwise modify Vishay's terms and conditions of purchase, including but not limited to the warranty expressed therein.

Except as expressly indicated in writing, Vishay products are not designed for use in medical, life-saving, or life-sustaining applications or for any other application in which the failure of the Vishay product could result in personal injury or death. Customers using or selling Vishay products not expressly indicated for use in such applications do so at their own risk. Please contact authorized Vishay personnel to obtain written terms and conditions regarding products designed for such applications.

No license, express or implied, by estoppel or otherwise, to any intellectual property rights is granted by this document or by any conduct of Vishay. Product names and markings noted herein may be trademarks of their respective owners.

X-ON Electronics

Largest Supplier of Electrical and Electronic Components

Click to view similar products for MOSFET category:

Click to view products by Vishay manufacturer:

Other Similar products are found below:

614233C 648584F IRFD120 JANTX2N5237 2N7000 FCA20N60_F109 FDZ595PZ 2SK2545(Q,T) 405094E 423220D

TPCC8103,L1Q(CM MIC4420CM-TR VN1206L 614234A 715780A NTNS3166NZT5G SSM6J414TU,LF(T 751625C

IPS70R2K0CEAKMA1 BUK954R8-60E DMN3404LQ-7 NTE6400 SQJ402EP-T1-GE3 2SK2614(TE16L1,Q) 2N7002KW-FAI

DMN1017UCP3-7 EFC2J004NUZTDG ECH8691-TL-W FCAB21350L1 P85W28HP2F-7071 DMN1053UCP4-7 NTE221 NTE2384

NTE2903 NTE2941 NTE2945 NTE2946 NTE2960 NTE2967 NTE2969 NTE2976 NTE455 NTE6400A NTE2910 NTE2916 NTE2956

NTE2911 TK10A80W,S4X(S SSM6P69NU,LF DMP22D4UFO-7B